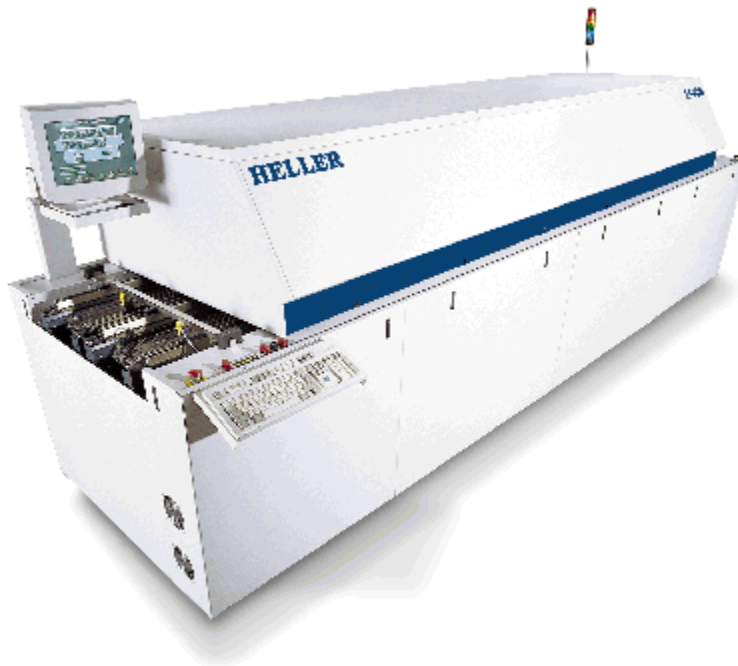


The new 1800EXL from Heller: today's design, tomorrow's features.



Model 1800EXL: Heller's solution to the challenges of increased productivity and greater flexibility.

The new Model 1800EXL demonstrates Heller's leadership in the reflow marketplace. We provide the most advanced reflow technology for your surface mount assembly line, while combining a more robust system with unmatched versatility and engineering expertise. For more information, call Heller Today.

The 1800EXL- from Heller's newest generation of reflow ovens- provides 25% higher airflow for enhanced temperature uniformity, repeatability and high-load handling. The 1800EXL features Heller's new, enlarged heating tunnel and baffle-free design, for six-sigma consistency, zone-to-zone and oven-to-oven. It also provides more flexibility in board handling, more robust construction and a more streamlined appearance.

The 1800EXL supports high-speed, high-volume throughput... at speeds up to 40 inches (one meter) per minute... while conserving valuable factory floor space. Rapid response times and precise temperature controls assure process uniformity, regardless of component density or board loading, with identical profile performance in either air or nitrogen.

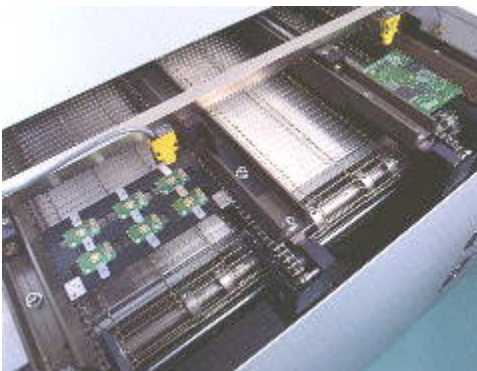
For higher heat transfer

rates, increased productivity and greater footprint, specify Heller's new Model 1800EXL.

[Additional Literature](#)

Heller 1800EXL versatility: single or dual-rail edge hold conveyor

With a high-capacity, 26-inch-wide (66 cm) tunnel, the 1800EXL offers unmatched flexibility in board handling. The oven may be fitted with an adjustable single-rail edge hold conveyor, to carry even the largest boards or multi-board panels, up to 23.5 inches wide (60 cm), through the oven.



To maximize flexibility, 1800EXL users may specify width-adjustable single edge hold conveyor or dual-rail edge hold conveyor with each side independently adjustable for width and speed.

The 1800EXL may also be configured with a dual-rail edge hold conveyor; each side is independently adjustable to convey boards as wide as ten inches (25.4 cm). Computer-controlled automatic adjustment of conveyor width is available as an option for both conveyor types.

The speed of each rail is also independently adjustable, allowing for two distinct temperature profiles to run simultaneously in the oven thus supporting both reflow and snap curing. The ability to convey two production lines concurrently, processing any combination of board sizes and conveyor speeds, can eliminate the need and the space requirement for a second oven.

The Heller 1800EXL: reflow advantages for every high-volume application

The Model 1800EXL combines sophisticated new design elements with the engineering expertise and reflow technology leadership you've come to expect from Heller:

- New, enlarged heating tunnels and baffle-free design for 25% higher airflow, enhanced temperature uniformity, repeatability and high-load handling.
- A more streamlined appearance, with integral CPU and keyboard, plus robust, heavy-duty construction for years of reliable service.
- Module response of less than one second to temperature changes of less than 0.1°C, thereby maintaining profile integrity for heavy board loads.
- Single edge hold conveyor adjustable for boards as wide as 23.5 inches (60cm)... or a dual-rail edge hold conveyor; each side is independently speed-adjustable for boards as wide as 10 inches (25.4 cm).
- Total forced convection using air or inert atmosphere, with nitrogen consumption levels as low as 850 SCFH* (23.8 m³/hour) at 25 PPM.
- Auto hood lift for effortless raising of the tunnel clamshell.
- PC-driven PID closed-loop controller capable for networking in a CIM environment.



Clean wiring and sleek design characterize the interior as well as the exterior of the 1800EXL

- Available with optional *Ultra Low* (Patent Pending) design, to reduce nitrogen consumption to less than 350 SCHF* (10m³/hour).
- Optimal thermocouple location in the air stream for fast response and accurate zone temperature control.
- Rapid profiling changes plus fast warm-up and cool-down.
- Wide process window for "universal profiling"- allows many different boards to be run on a single temperature profile .
- Advanced five-thermocouple board profiling and process parameter logging capability with the capacity to store up to 500 temperature recipes and 500 profile graphs.
- Resourceful engineering and flexible design to support customized solutions to unique process requirements.
- Worldwide, leading-edge support: optional RMATS (Remote Modem-Accessible Technical Support) with global video links for direct access to a factory-based Heller engineer.
- GEM/SECS II interface software is available for an optional feature.

** Depends upon PCB size and oven configuration.*

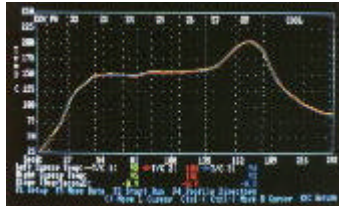


Single exhaust port for easy facilities interface and consistent profiling

A *complete* approach to reflow technology is what makes Heller the world class leader.

System Features:

- The most efficient heat transfer, from extra high-volume, high-velocity, heating modules, producing temperature gradients of less than 2°C throughout the oven.
- Instant-response heating modules that react in less than one second to temperature changes of less than 0.1°C to maintain profile integrity for heavy board loads.
- Six-sigma reliability for the most demanding production environments.
- Single or dual-rail edge hold conveyor for greater versatility in board handling.
- User-friendly Windows™ software.



Pure convection technology provides flexibility to produce any solder paste manufacturer's recommended profile.

Lifetime Warranty:

- Lifetime warranty on all heater elements
- Lifetime warranty on all blower motors